



數位系統之低功率設計技術簡介

Introduction to Low-Power Design Techniques for Digital Systems

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Heterogeneous Integration

教育部顧問室
SOC人才培育計畫



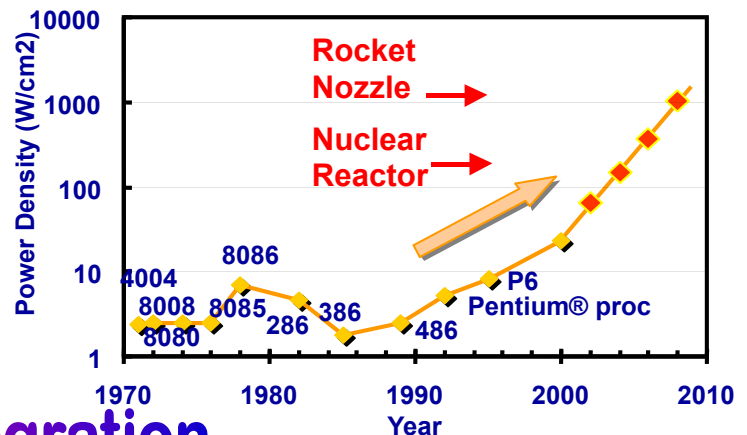
Outline

- **Introduction**
- **Multiple Power Domains**
- **Dynamic Voltage and Frequency Scaling**
- **Clock Gating**
- **Dual Threshold Voltages**
- **Power Gating**
- **Conclusion**

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Motivation

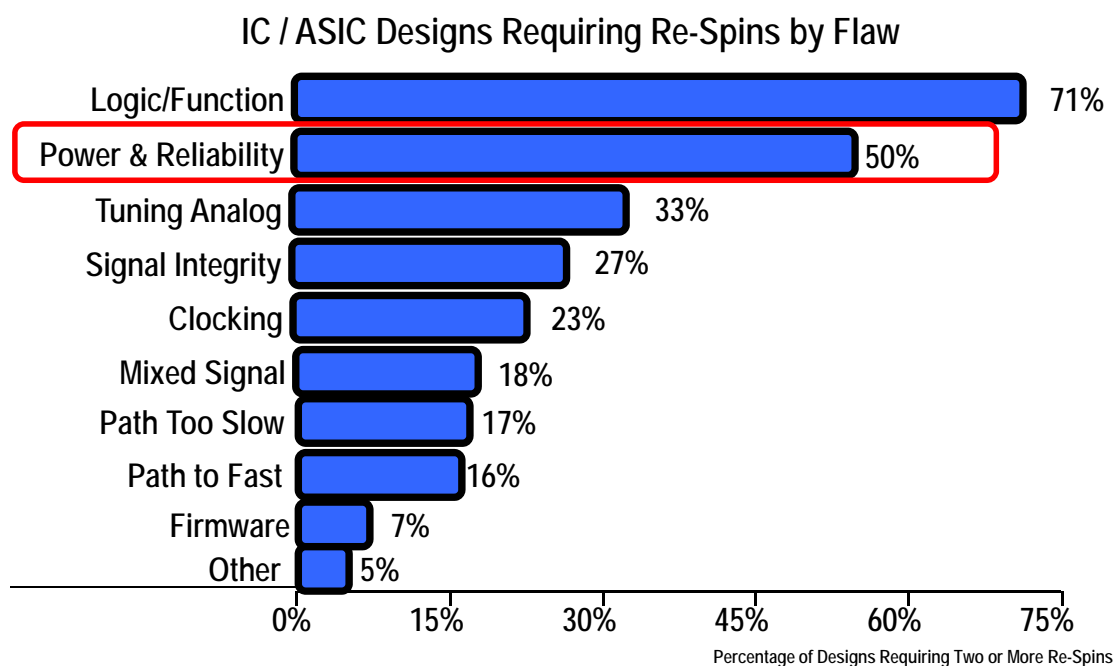
- **Portability requirement is increasing**
 - Longer battery life with increased functionality
- **Power related issues are getting serious**
 - Heat dissipation requirement (rocket nozzle?)
 - Electromigration
 - Power/Ground bounce due to IR-drop
- **Power is as important as performance**
 - Should be considered in the design phase



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Source: Courtesy, Intel P. 3

Serious Power-Related Issues



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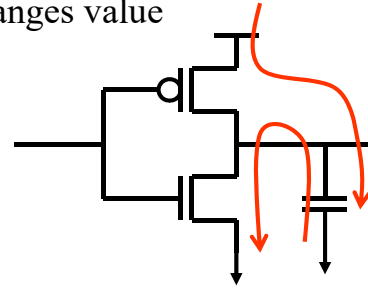
Source: Courtesy, Synopsys

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Where is Power Consumed?

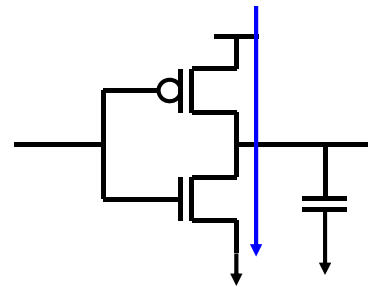
- **Dynamic power (switching power)**

- Power consumed when the output of a gate changes value
- Quadratically dependent on voltage
- $P = C_L V_{dd}^2 f$
- C_L : loading capacitance; V_{dd} : supply voltage
- f : transition frequency



- **Static power (leakage power)**

- Power consumed by each element at all times
 - From several sources
- Grows exponentially when voltage is reduced
- Increases as transistor size shrinks

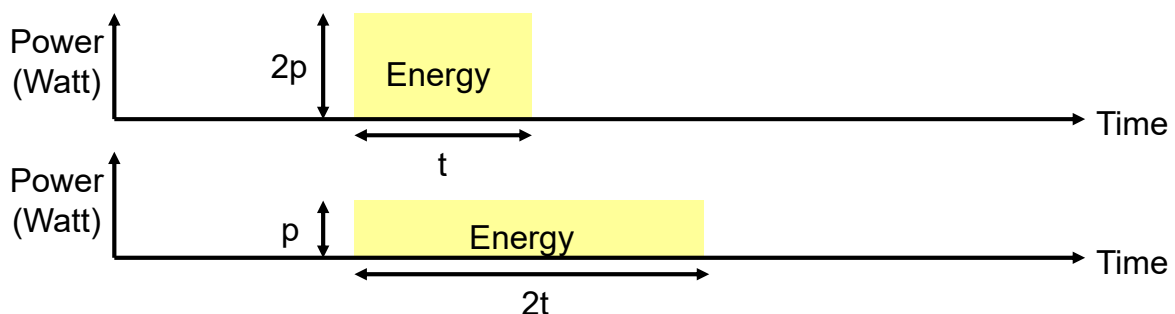


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Power Vs. Energy

$$Power = \frac{Energy}{T}$$



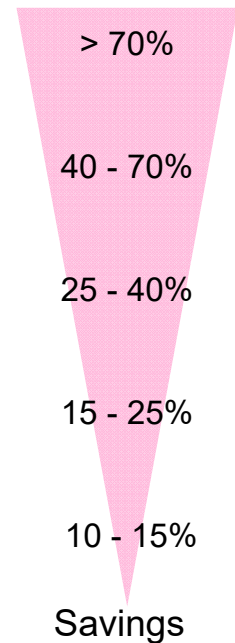
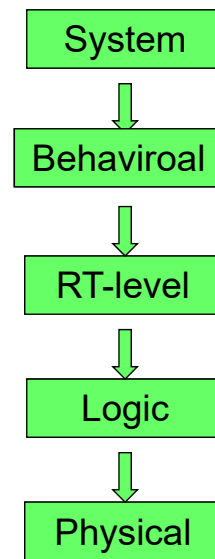
- Two approaches require the same energy
- Lower power design could simply be slowed down ??

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Power Saving Opportunities

- A power-conscious design methodology addresses power at every level of design hierarchy
- Applying low-power techniques at higher design levels can reduce more power
- The focuses of this slide are the low-power technique at RTL or higher design levels



Ref : [1]

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Power Reduction Techniques

- Reduce supply voltage ($V_{dd}\downarrow$)
 - Multiple power domains
 - Lower V_{dd} value for non-critical blocks
- Reduce signal transitions ($f\downarrow$)
 - Dynamic voltage and frequency scaling (DVFS)
 - Reduce frequency for light-loading blocks
 - Clock gating
 - Freeze clock signal
- Use high-Vt cells for lower leakage power ($leakage\downarrow$)
 - Dual threshold voltages
 - Replace the cells on non-critical paths with high-VT cell
- Shut down power supply when not used ($V_{dd}\downarrow$, $leakage\downarrow$)
 - Power gating (MTCMOS)

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Outline

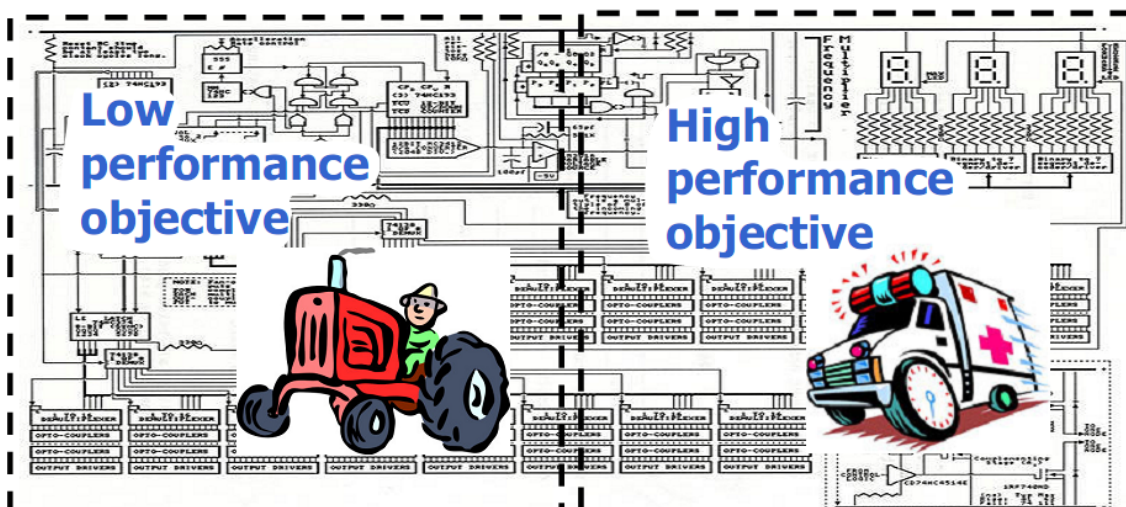
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Multiple Power Domain Concept

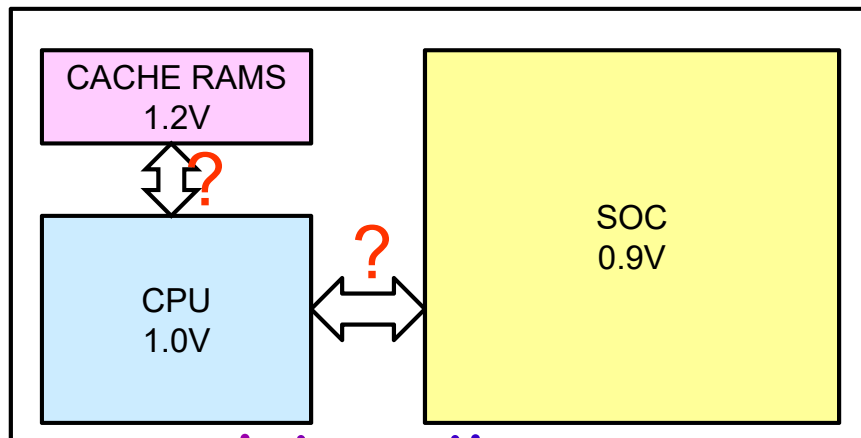
- Different components run with different voltages
- Also known as multi-supply-voltage (MSV) designs



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Adv. of Multiple Power Domains

- Since dynamic power is proportional to V_{dd}^2 , lowering V_{dd} on selected blocks helps reduce power significantly.
- Unfortunately, lowering the voltage also **increases the delay** of the gates in the design
- Level shifters are used to propagate the signals between different domains



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Basic MSV Design Principles

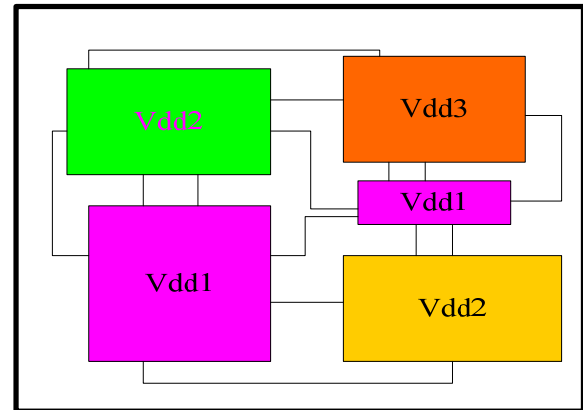
- Adopt multiple supply voltages (MSV) to trade performance and power saving
- Assign higher VDD to **timing-critical** cells for timing optimization
 - **GOOD** for performance
 - **BAD** in power consumption
- Assign lower VDD to **non-timing-critical** cells for power saving
 - **BAD** for performance
 - **GOOD** in power consumption

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Physical Implementation Requirements

- The devices with the same supply voltage will be put together
 - Form a “voltage island”
- Creation of voltage islands
 - During high-level synthesis or physical synthesis
- Physical implementation
 - Floorplanning of voltage islands
 - Power network planning
- As few voltage levels as possible
 - Reduce the types of level shifters and ease the power/ground distribution
 - Level shifter itself occupies area and consumes power
 - Level shifter takes time to switch
 - increases delay



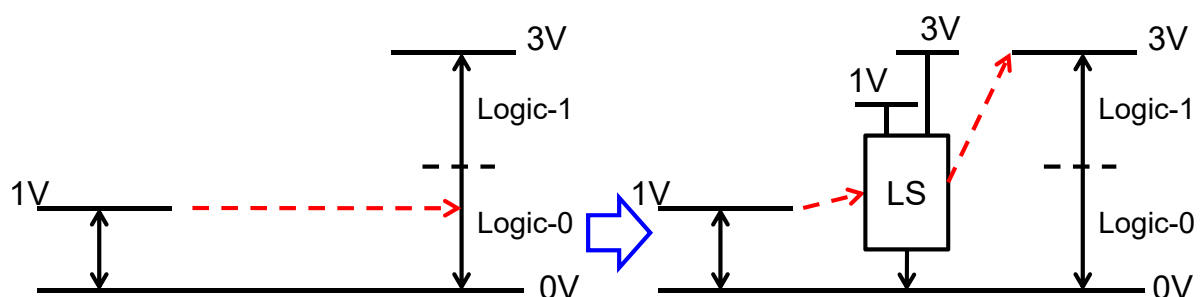
Three supply voltages and five voltage islands

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Low-to-High Level Shifter – Case 1

- 1V swing may not reach threshold in the 3V domain
 - ➔ Add Level Shifters

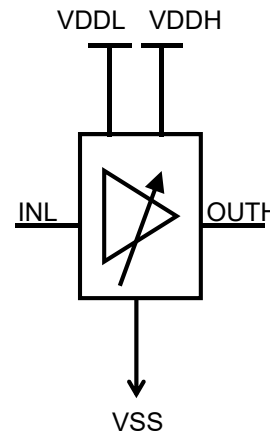
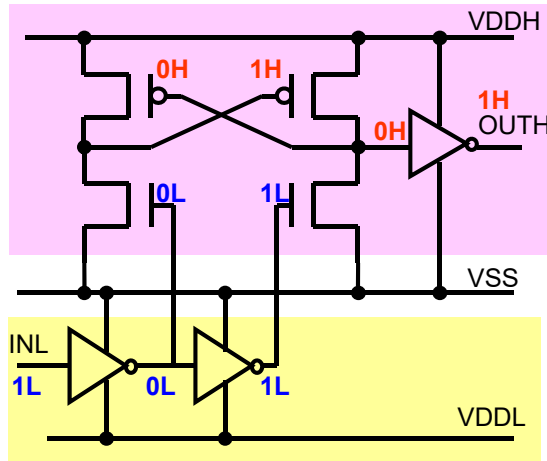


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Low-to-High Level Shifter – Case 1

- “Up-shifting” level converters require two supply rails and share a common ground



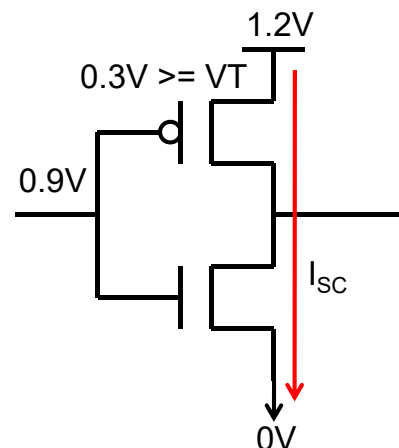
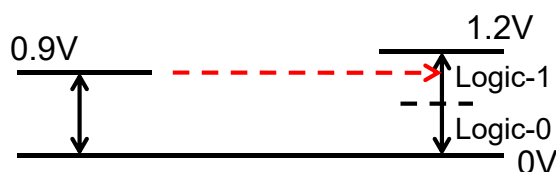
Ref:[2]

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Low-to-High Level Shifter – Case 2

- A 0.9V signal driving a 1.2V gate will turn on both the NMOS and PMOS networks, causing short-circuit currents

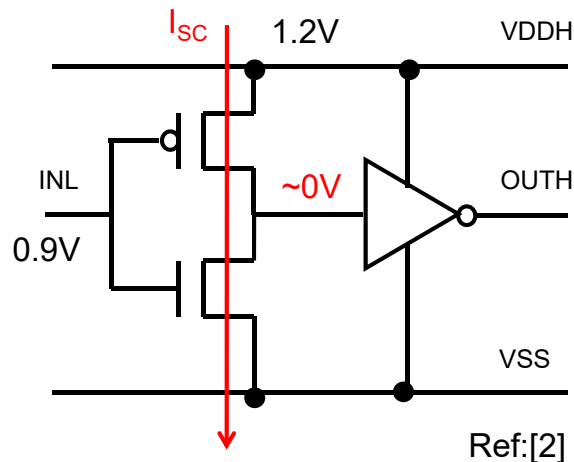


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Low-to-High Level Shifter – Case 2

- A low voltage swing input signal would not necessarily be strong enough to turn the NMOS input transistor fully on.
 - Internal signal cannot be discharged to 0V

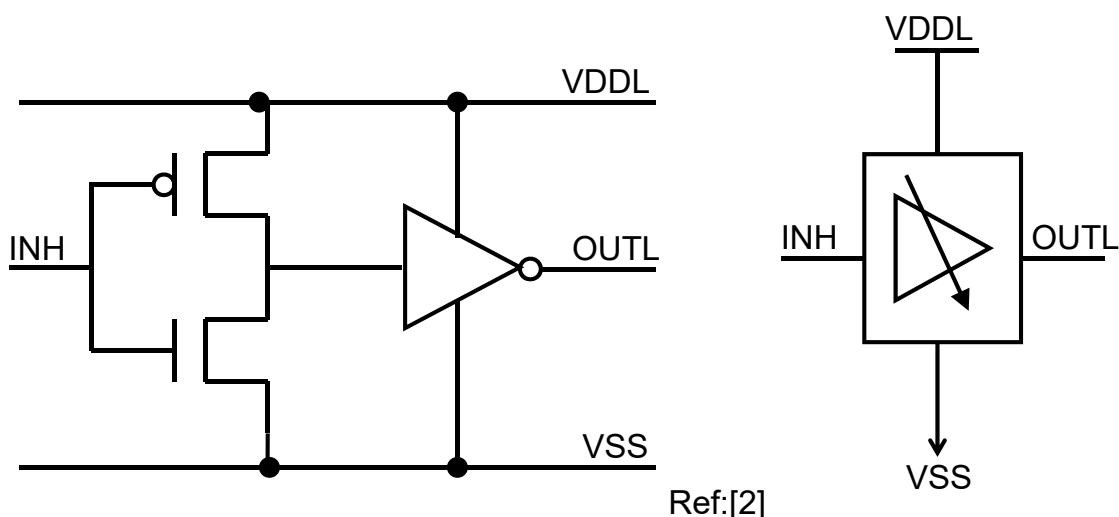


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High-to-Low Level Shifter

- CMOS gate can be driven higher than the power supply voltage without problems, up to the gate breakdown voltage
 - Additional level shifter is not required

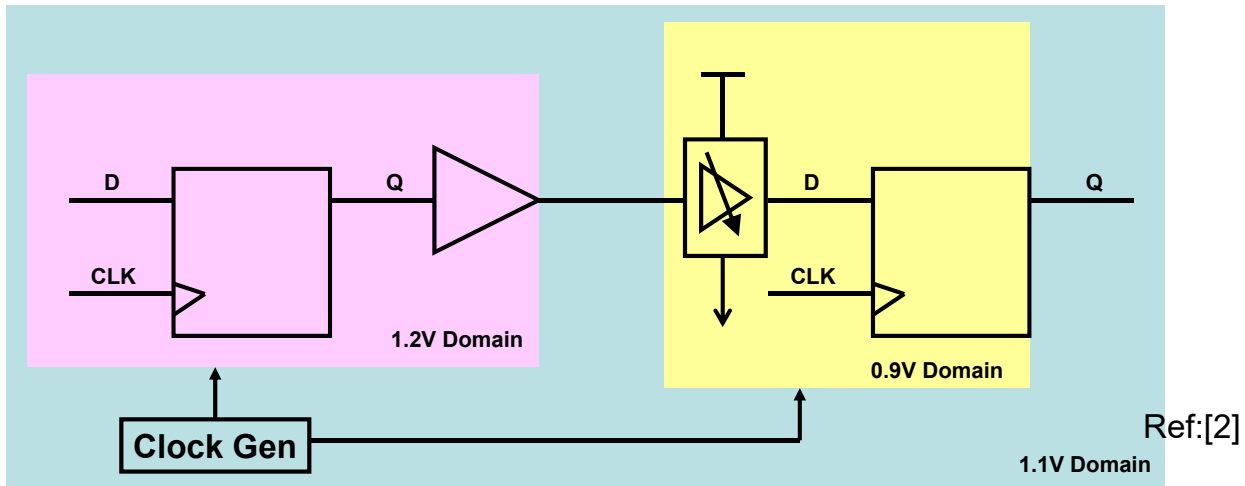


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Timing Issues

- **Gate delay is different with different supply voltages**
 - Clock arrival time may be quite different, too
 - Level shifters will induce extra delay as well
 - Timing analysis becomes more complex
- **Optimization with accurate timing analysis**



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Other Issues in MSV Approach

- **Level shifter design**
 - Reduce its power, area, and delay
- **Library characterization**
 - Support every possible supply voltages in a library requires too much characterization efforts
 - When a cell is running at different voltage that are not characterized in the library, timing analysis becomes much more complex
- **Floorplanning, power planning, power grids**
 - Voltage-island awareness is a new consideration in physical design
 - Reduce the required level shifters is an additional target
- **Power up and power down sequencing**
 - A pre-designed sequence for powering up the design may be required to avoid deadlock

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Dynamic Voltage & Frequency Scaling

- **Dynamically control the voltage and frequency**
 - Increase voltage when high performance is required
 - Reduce the voltage when not needed
- **DVFS is a method to reduce the energy for a task by scaling the operating voltage/frequency**
 - Power consumption if a CMOS-based circuit is

$$P = \alpha \cdot C \cdot V^2 \cdot f$$

*α : switching factor
 C : effective capacitance
 V : operating voltage
 f : operating frequency*

- Energy required to run a task during T is

$$E = P \cdot T \propto V^2 \quad \text{Assuming } V \propto f, T \propto f^{-1}$$

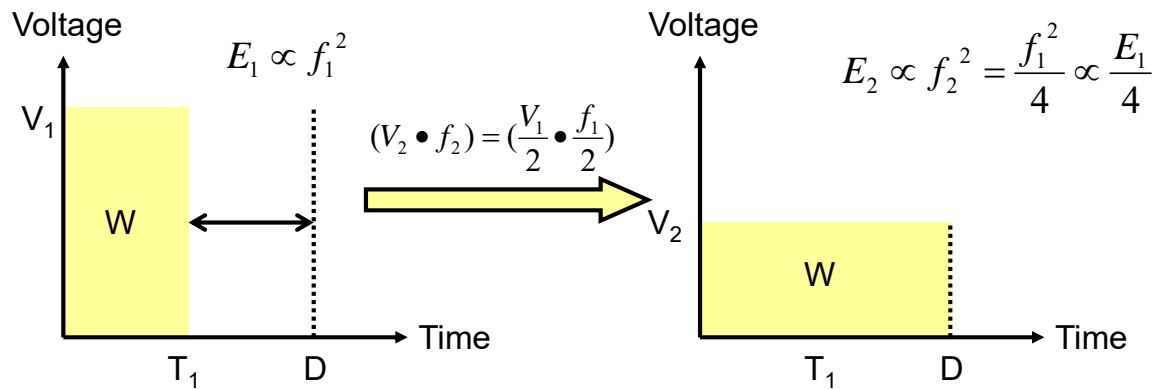
- **By lowering CPU frequency, CPU energy can be reduced**

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Energy Reduction with DVFS

- **Ex:** a task with workload W should be completed by a deadline, D



- DVFS reduces the CPU energy by providing “just enough” computation power

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Choosing a Frequency in DVFS

- Workload of a task, W_{task} is defined as the total number of CPU clock cycles required to finish the task.

$$W_{\text{task}} = \sum_{i=1}^N CPI_i$$

N : total number of instructions in a task
 CPI : clock cycles per instruction

- Task execution time, T_{task} is a function of the CPU frequency, f_{CPU}

$$T_{\text{task}} = \frac{W_{\text{task}}}{f_{\text{CPU}}}$$

- Given a deadline of D , f_{target} denotes the CPU frequency that results in T_{task} closest to D

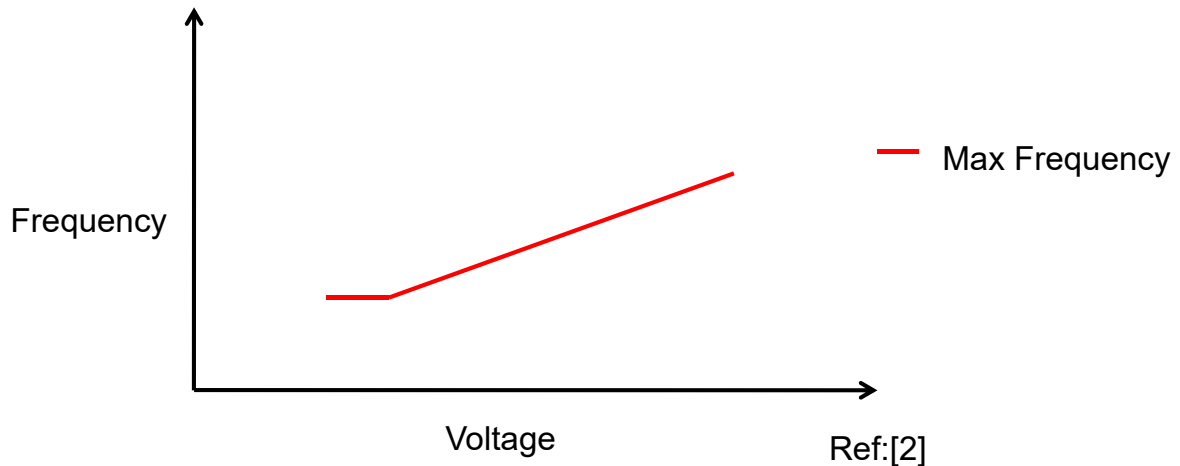
$$f_{\text{target}} = \frac{W_{\text{task}}}{D} \Rightarrow T_{\text{task}} = D$$

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Dynamic Operating Voltage Range

- **Best operation region is the period that frequency increases monotonically over voltage**
 - Make sure the circuits can operate reliably and the delay paths vary monotonically

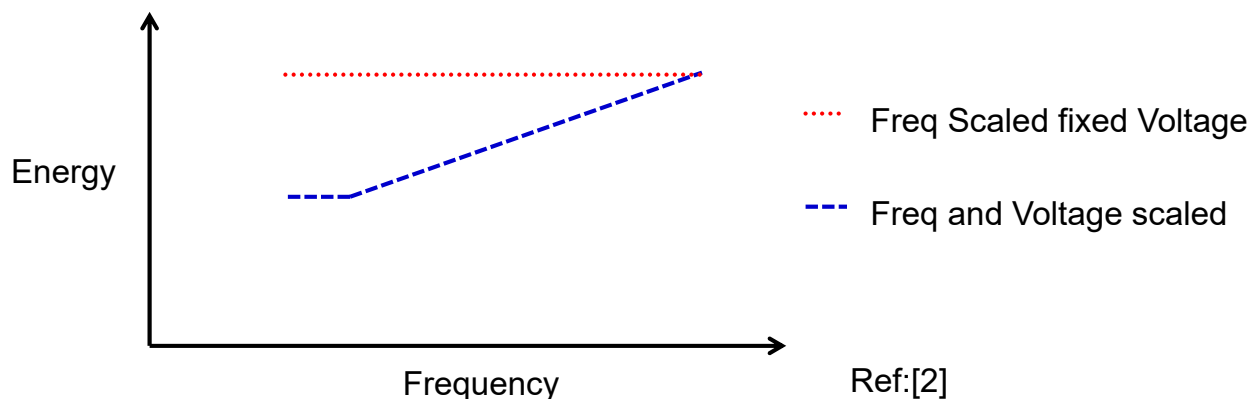


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Dynamic Energy Dissipation

- **Energy is the integration of power over the time taken to complete a task of work**
 - Lowering frequency can reduce power, but total energy is the same
- **Lowering the supply voltage can reduce the energy dissipation simultaneously**

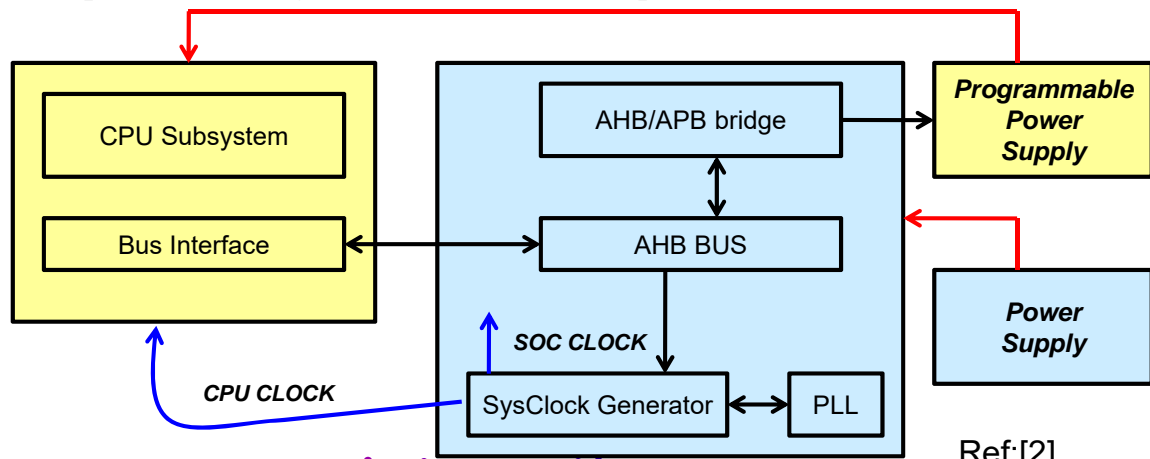


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DVFS Block Diagram

- **Supply Voltage**
 - The CPU subsystem is powered by a programmable power supply.
 - The rest of the chip is powered by fixed power supply
- **System Clock**
 - The SysClock Generator dynamically control the PLL to generate required clock signals with different frequency

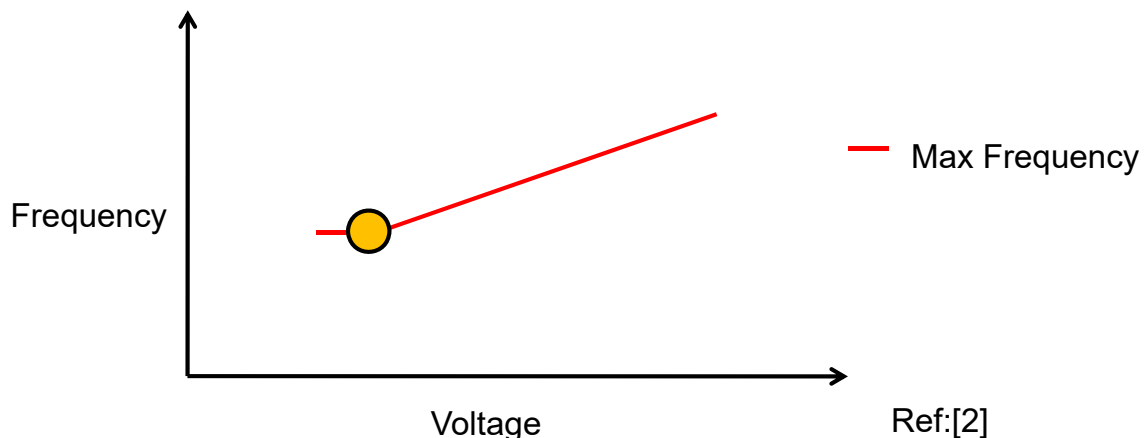


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Minimum Operating Point

- **Decide the minimum CPU clock speed that meets the workload requirements**
- **Decide the lowest supply voltage that will support that clock speed**

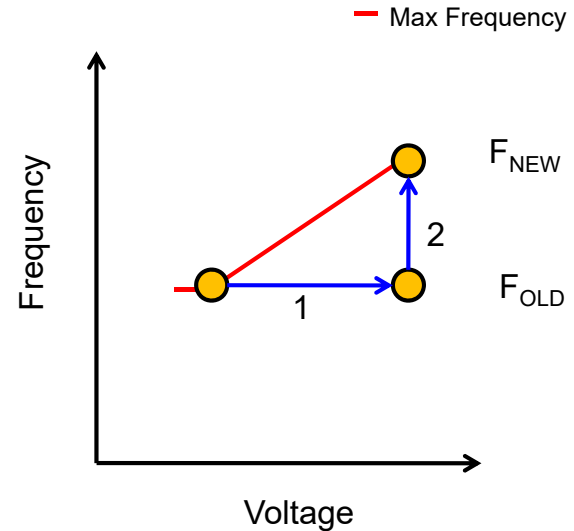
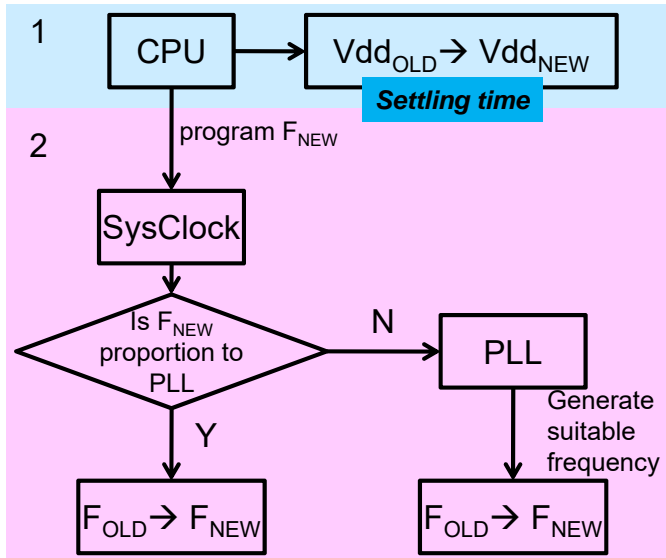


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DVFS Operation ($F_{NEW} > F_{OLD}$)

- The target clock is higher than current clock
 - Supply voltage increases
 - Clock frequency increases

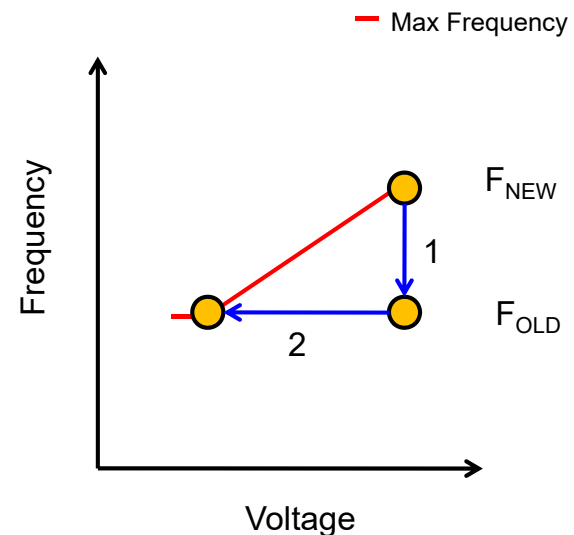
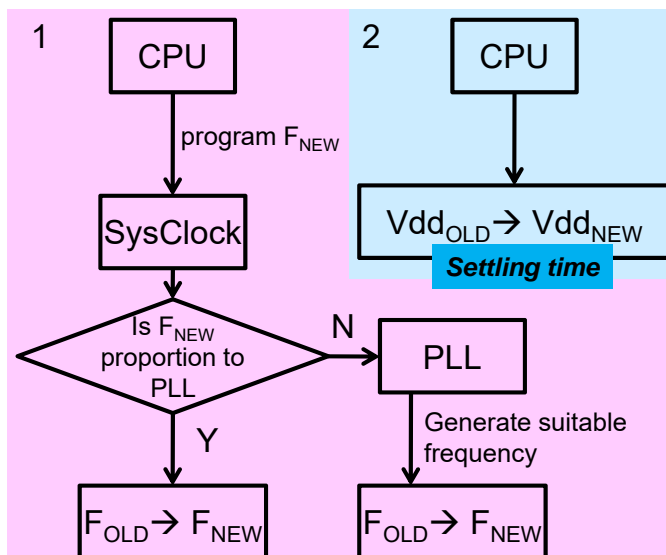


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DVFS Operation ($F_{NEW} < F_{OLD}$)

- The target clock is lower than current clock.
 - Clock frequency decreases
 - Supply voltage decreases

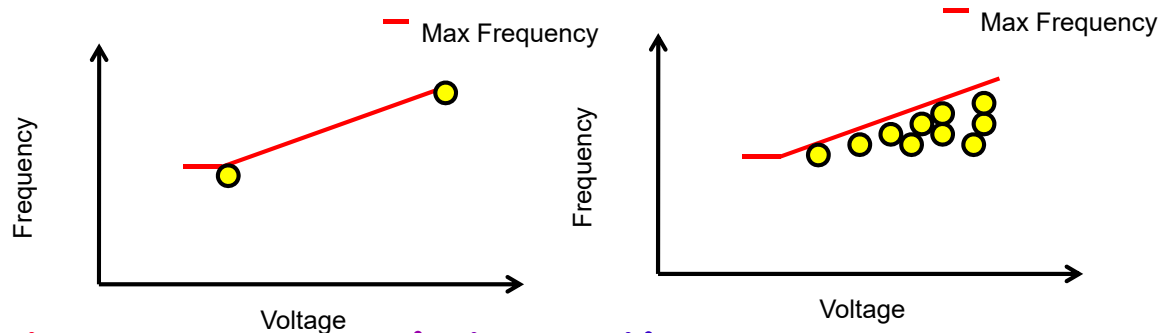


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DVFS Implementation Issues

- **Determining which voltages and clock values to support**
 - Too few operating points
 - Spend a significant time ramping between two levels
 - The energy saving efficiency during the ramping times are less than the steady-state values
 - Too many operating points
 - Power supply will spend most of time “hunting” between different target voltage levels



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Clock Speed/Supply Voltage Values

- **Rules to determine the number of operating points**
 - What are the appropriate clock **frequencies** for different **workloads**
 - Which frequencies have clock periods that are multiples of the PLL period
 - Just change **the clock divider**, not the PLL frequency
 - What **voltage** is required to support **each target frequency**
- **Refine the selection of operating points**
 - An FPGA implementation
 - High level simulation model

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Other DVFS Issues

- **Determining the minimum voltage to meet a particular (sub)system performance level**
- **Achieving timing closure over a range of voltages and clock speeds**
- **Control sequencing (power management)**
- **Generate required clock speed/supply voltage values**
- **Verification across different situations**
 - Especially at transition cases

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Outline

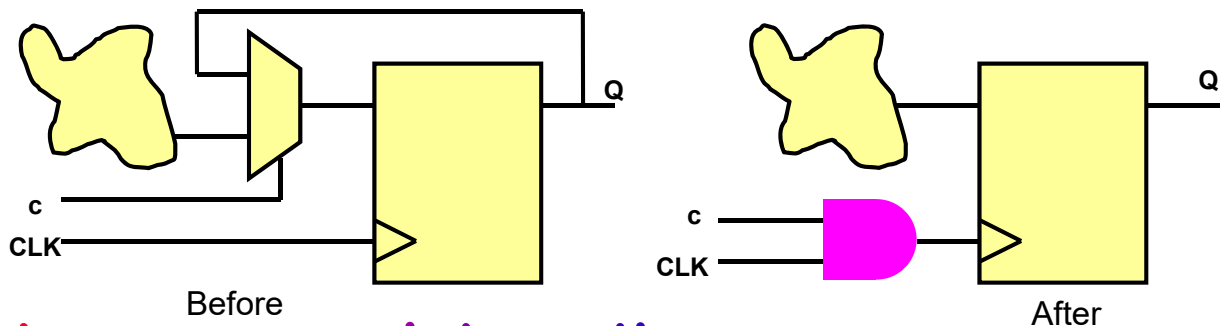
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Clock Gating (1/2)

- **Up to 50% or even more of the dynamic power in a chip is in the distribution network of the clock**
 - Clock buffers have the highest toggle rate in the system
 - Typically there are lots of clock in a design
 - Clock buffers often have a high driving strength to minimize clock delay
- **The most common technique to reduce this power is to turn clocks off when they are not required → Clock Gating**
 - No need for Muxes to re-circulate the data for these flip-flops

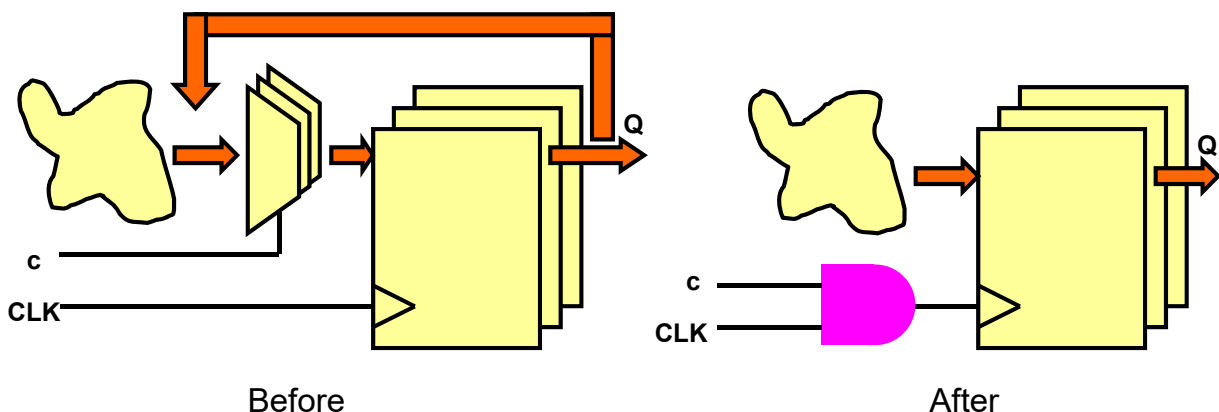


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Clock Gating (2/2)

- **Much more effective if the same gating function is applied to large set of registers**

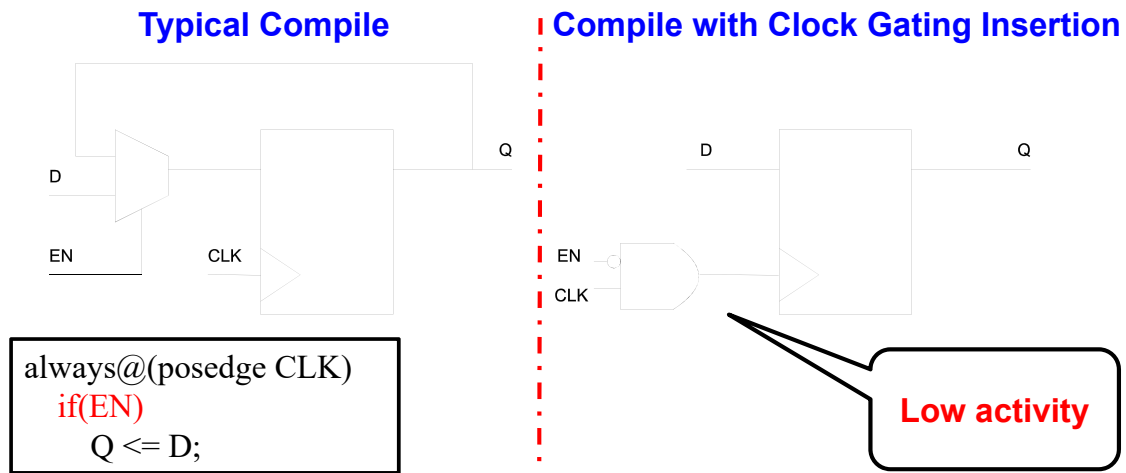


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How Clock Gating Works ?

- In the original RTL, the register is updated or not depending on a variable (EN)
- The same result can be achieved by gating the clock based on the same variable

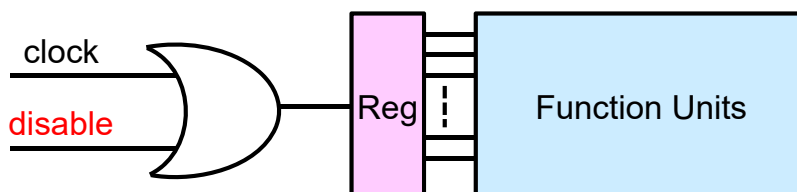


Ref:[2]
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Issues of Clock Gating

- Clock gating also idle the succeeding functional units
- Need logic to generate *disable* signal
 - Increase the complexity of control logic
 - Timing critical to avoid glitches at OR gate output
- Additional gate delay on clock signal
 - Gated OR gate can replace a buffer in the clock distribution tree
- May generate an extra clock edge while *disable* is deasserted
 - (clock=0, disable=1) \rightarrow 1 ; (clock=0, disable=0) \rightarrow 0
 - Should be careful about the deassertion time



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Clock Gating Levels

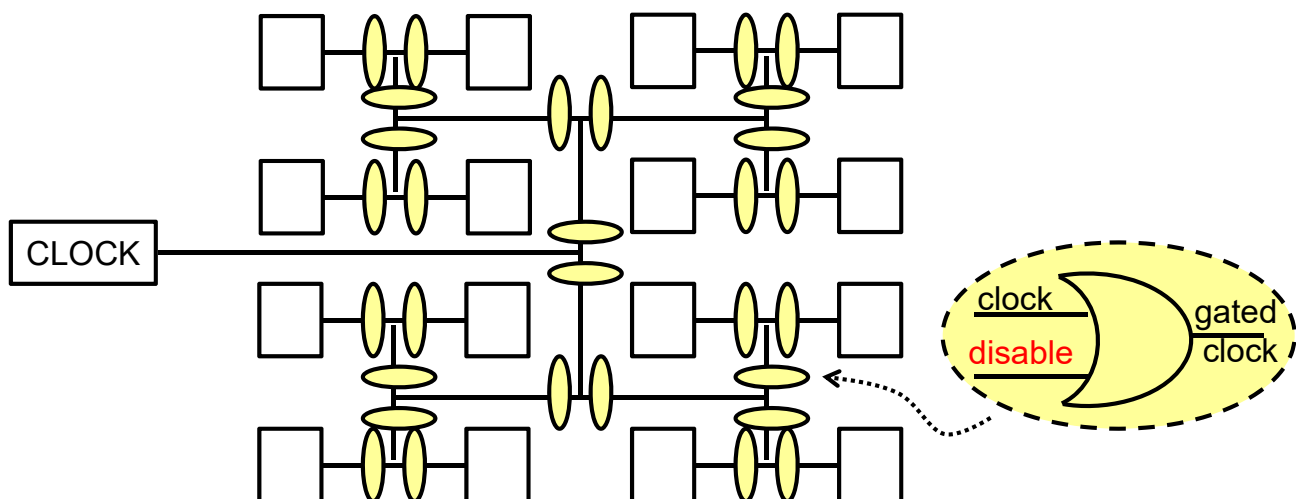
- **Fine Grain**
 - Portions of the pipeline registers are disabled depending on whether the information they hold is used in the next stage
- **Medium Grain**
 - Disable cache pre-charging during cache miss
- **Coarse Grain**
 - Eliminate switching of the clock's main driver
- **Depending on the target applications**

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Gated Clock Distribution

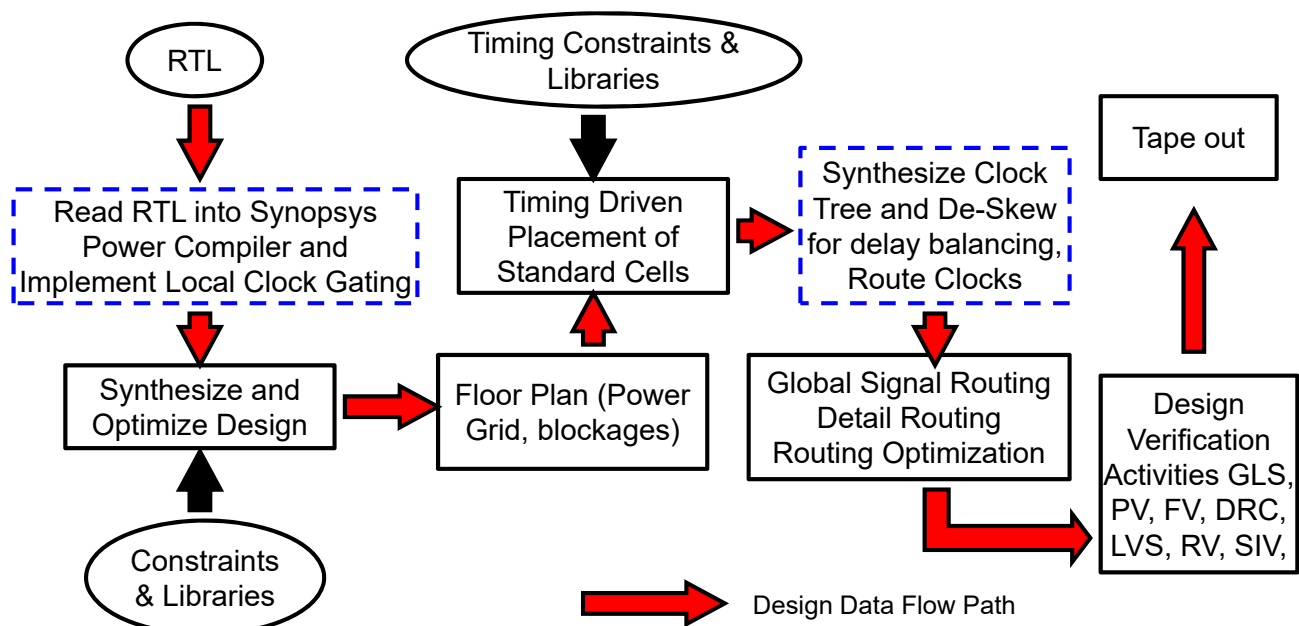
- **If the paths are perfectly balanced, clock skew is zero**
 - Can insert clock gating at multiple levels in clock tree
 - Can shut off entire sub-tree if all gating conditions are satisfied



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Clock Gating in the Design Flow

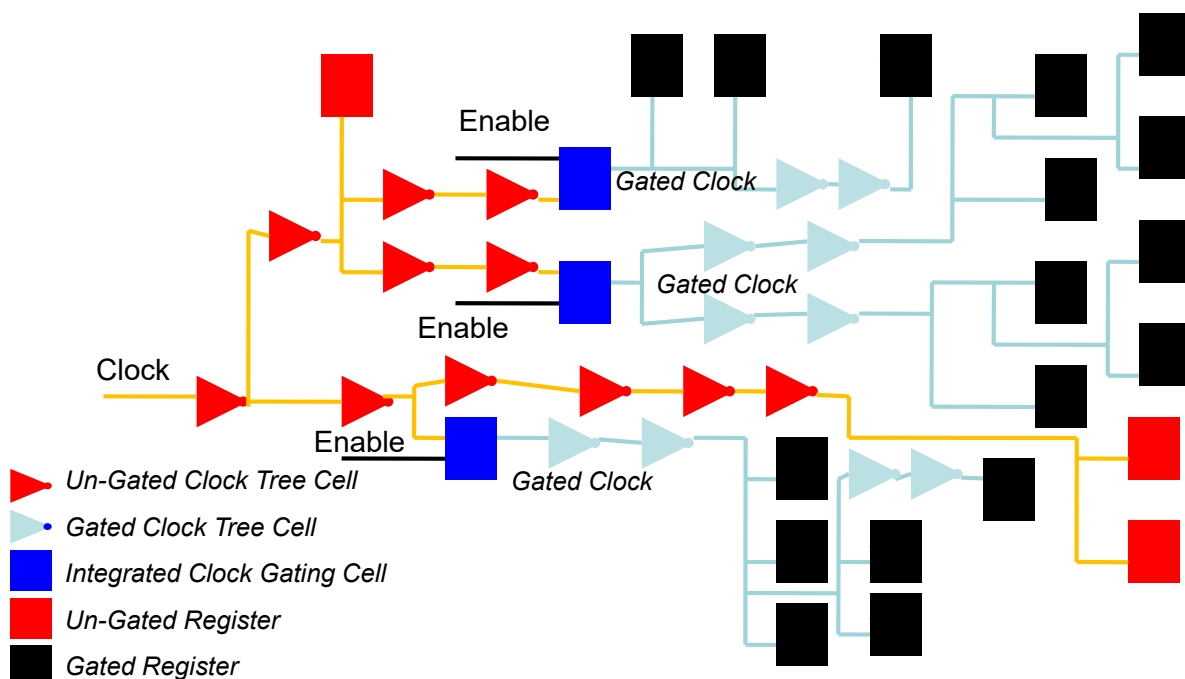


Ref:[3]

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Clock Gating Example



Ref:[3]

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Other Clock Gating Issues

- **Where and when can we gate the clock?**
 - Find suitable gating functions for many latches
- **Need careful checking to prevent the function being changed**
 - Formal equivalence checking may be a solution
 - Scalability of sequential equivalence checking is a problem
- **Do we really reduce power?**
 - Need better power estimation capabilities to consider clock gating effects

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Outline

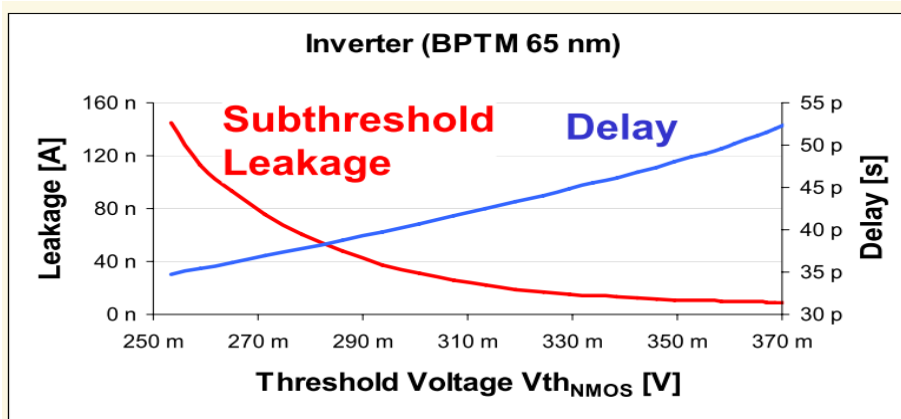
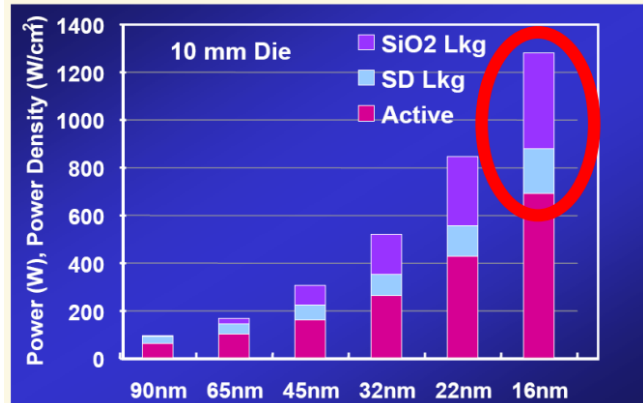
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Leakage Power Reduction

- Leakage power dissipation has become a major part in advance process
- Reducing V_t can reduce the leakage current
 - Also reducing performance



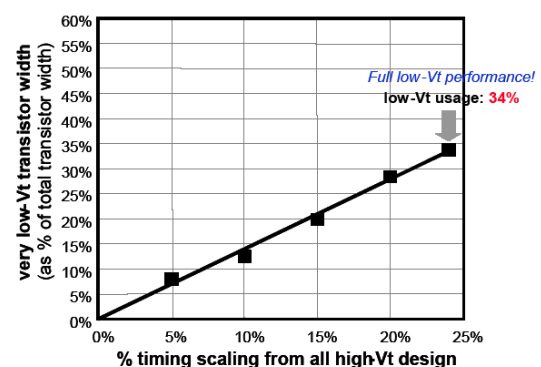
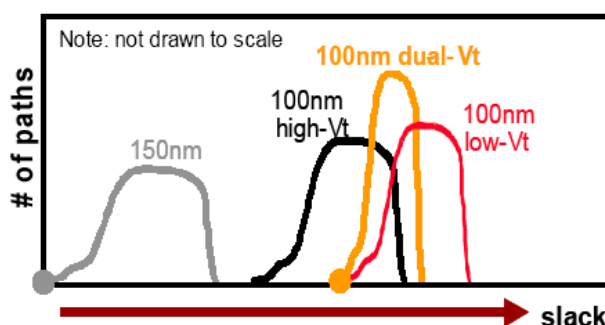
SiO2 Lkg : Gate Oxide Tunneling Leakage
SD Lkg : Sub-threshold Leakage

Ref: [4]

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Dual-VT Design for Leakage Control

- “Dual VT” is a technique to minimize the total number of fast, leaky low-VT cells by deploying them only when required to meet timing
- Dual-VT can increase timing slack and also can reduce the leakage power

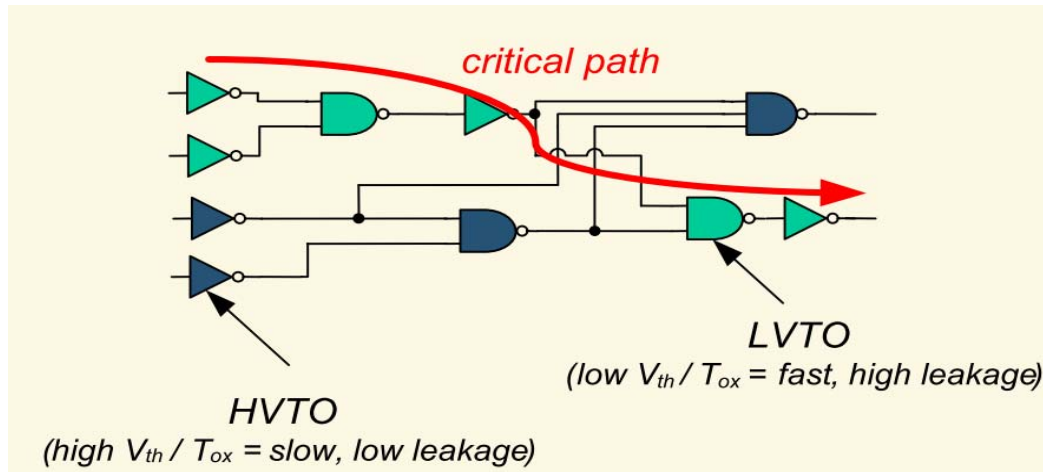


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Dual-Threshold Voltage (Dual-VT)

- **Dual Threshold Voltage CMOS (DVTCMOS)**
 - Use lower threshold for devices within the critical paths
 - Use higher threshold for devices outside the critical paths
- ➔ **Decrease leakage power without performance penalty**



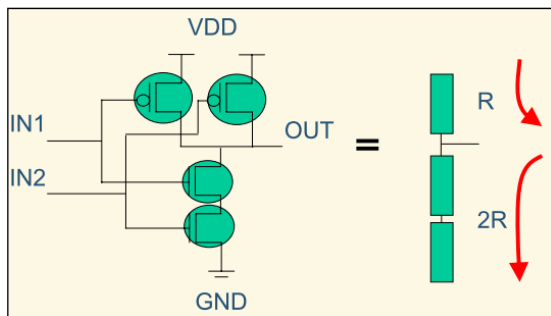
Ref: [4]

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Mixed-Vt Gates

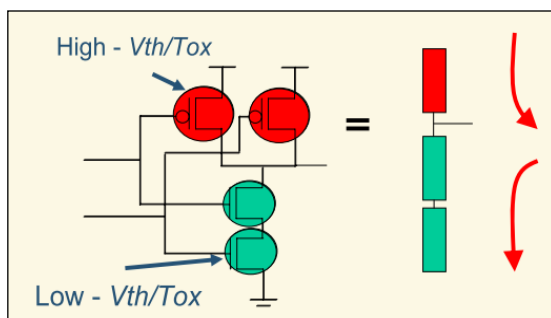
- **Preserve the delay while decreasing the leakage**



0→1 delay
(Output from GND to VDD)

1→0 delay
(Output from VDD to GND)

➔ **$\text{delay}_{0 \rightarrow 1} < \text{delay}_{1 \rightarrow 0}$**



Typical timing analysis

➔ only maximum delay is considered!!!!

Slow down the rising case

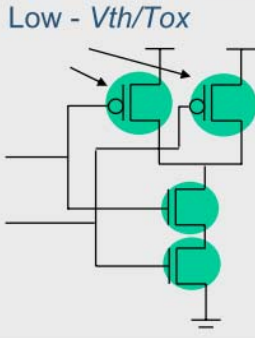
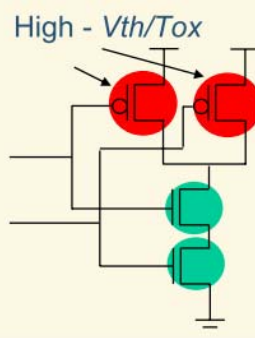
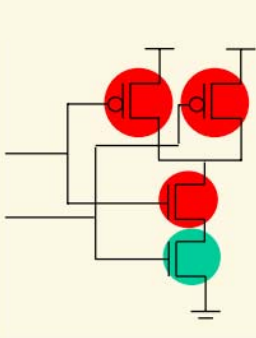
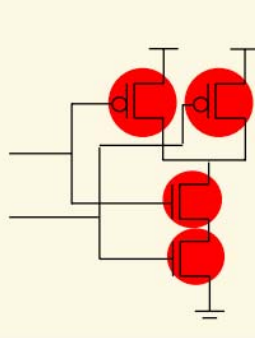
➔ **$\text{delay}_{0 \rightarrow 1} = \text{delay}_{1 \rightarrow 0}$**

Ref: [4]

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Example : Mixed-Vt Gates (NAND2)

 <p>Low - V_{th}/T_{ox}</p>	 <p>High - V_{th}/T_{ox}</p>		
LVTO gate <ul style="list-style-type: none">- rise time is shorter than fall time- <i>minimum delay cell</i>- <i>very high leakage</i>	F - MG gate <ul style="list-style-type: none">- rise and fall time are nearly the same- <i>minimum delay cell</i>- <i>high leakage</i>	MG gate <ul style="list-style-type: none">- <i>middle delay cell</i>- <i>middle leakage</i>	HVTO gate <ul style="list-style-type: none">- <i>maximum delay cell</i>- <i>minimum leakage</i>

Ref: [4]

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Summary of Dual-Vt CMOS

- **High-Vt cell VS low-Vt cell**
 - High-Vt cell has lower leakage current and lower performance
 - Low-Vt cell has higher performance and higher leakage current
- **Usually, there is a minimum performance which be met before optimizing power**
 - First, synthesizing with the highest performance, using low-Vt library
 - Then, swapping the cells on non-critical paths to low-leakage cells because their performance degradation will not affect the overall speed
- **Library supports for different Vt is an extra cost**
 - Similar to preparing two different library sets
- **Mixed-Vt gates combines the advantages of DVTCMOS at transistor level**
 - The cell library with Mixed-Vt gates is not popular yet

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Outline

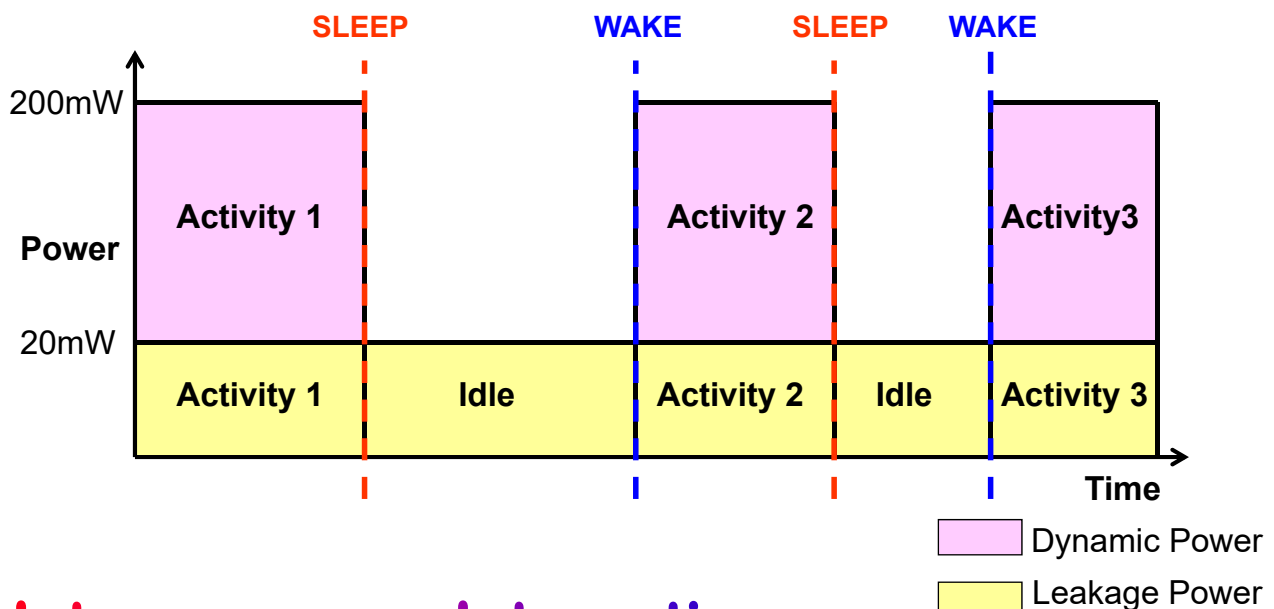
- Introduction
- Multiple Power Domains
- Dynamic Voltage and Frequency Scaling
- Clock Gating
- Dual Threshold Voltages
- **Power Gating**
- Conclusion

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Power Profiles (No Power Gating)

- SLEEP events initiate entry to the low power mode
- WAKE events initiate entry to active mode

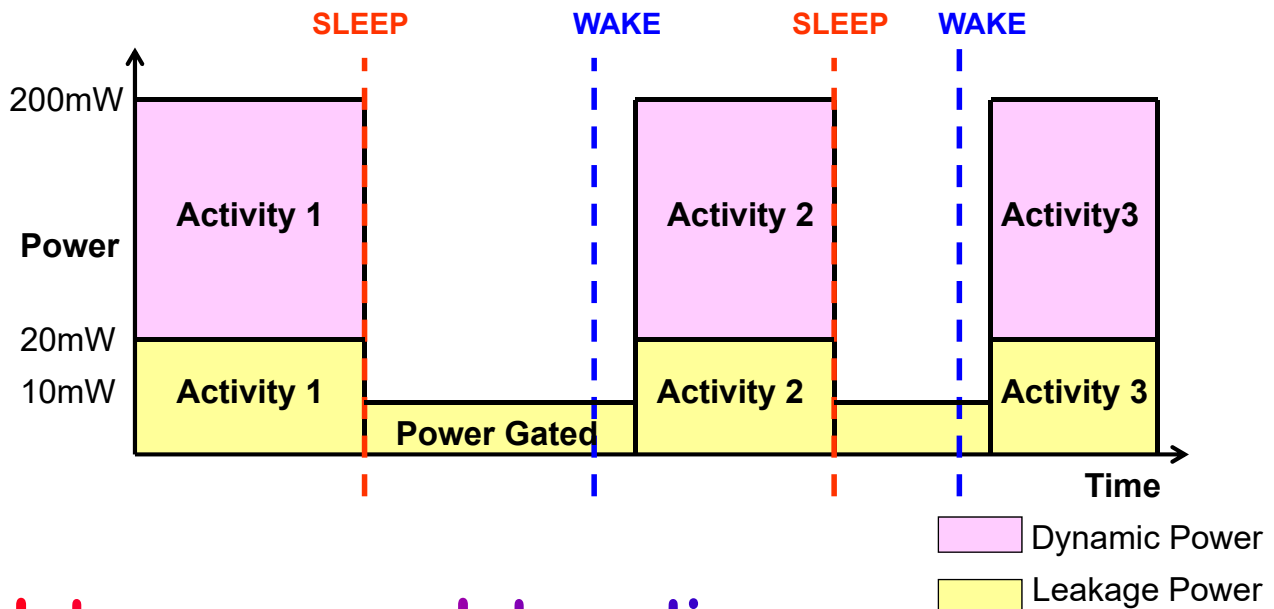


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Power Profiles (Power Gating)

- Power gating further reduces the standby power
- Require longer wakeup time in the WAKE event

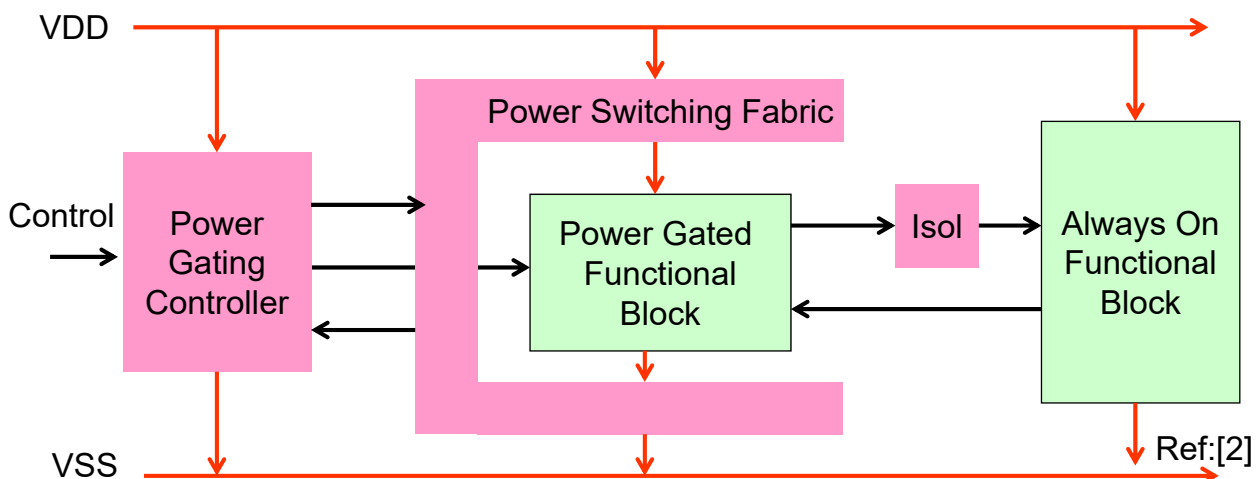


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Block Diagram of Power Gating Design

- The basic components are composed with
 - Power switching fabric
 - Isolation cell
 - Power gating controller

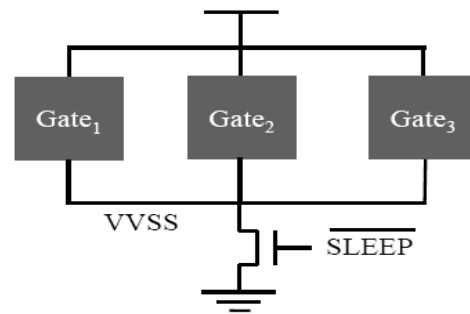
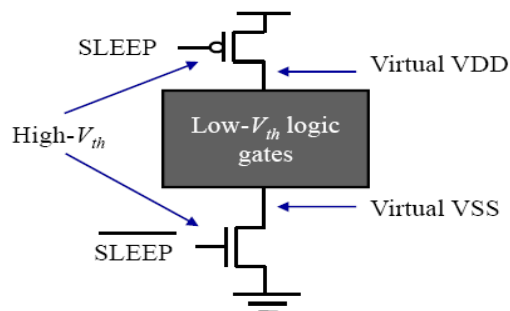


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Multi-Threshold-Voltage CMOS (MTCMOS)

- **High- V_{th} power switches are controlled by SLEEP signal**
 - Low- V_{th} logic gates are used to achieve high performance
 - Reduces leakage power dramatically due to the series-connected high- V_{th} power switch
- **Typically only a header or a footer sleep transistor is used.**
- **A single sleep transistor may be shared among several logic gates**



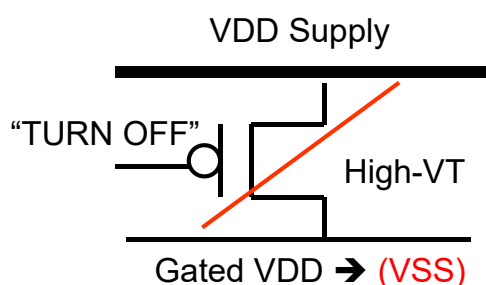
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Sleeper Transistor (MTCMOS)

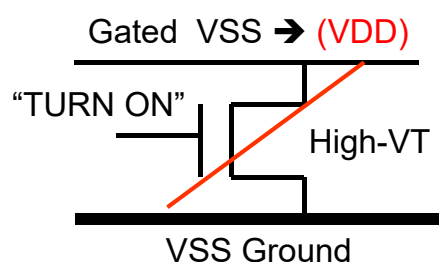
• Header

The internal nodes and outputs of a power gated block collapse down to the ground rail when the switch is turned off



• Footer

The internal nodes and outputs all charge to the supply rail when the switch is turned off

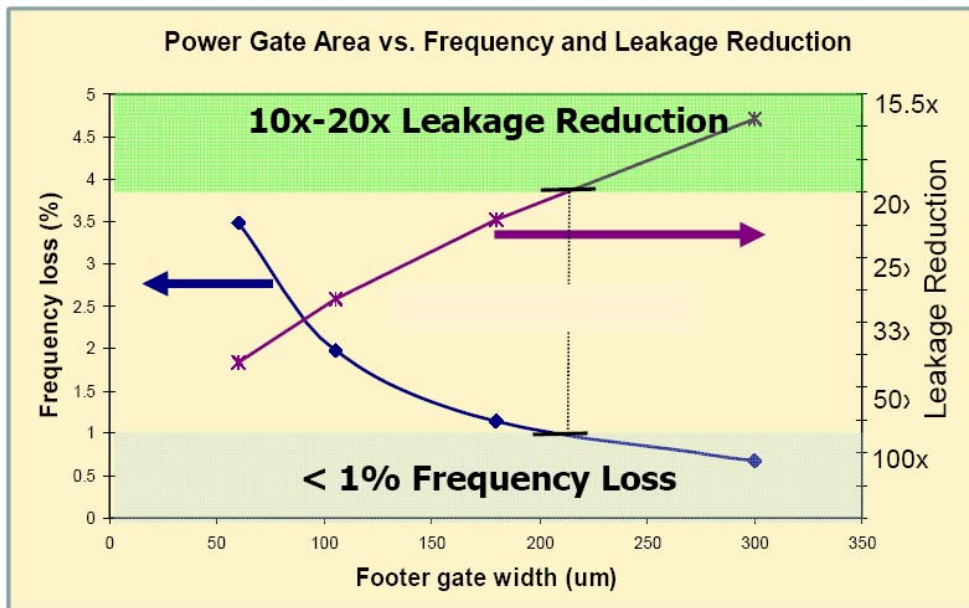


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Tradeoff on Sleep Transistor Sizing

- Maximize the saving of power consumption
- Minimize the impact of performance



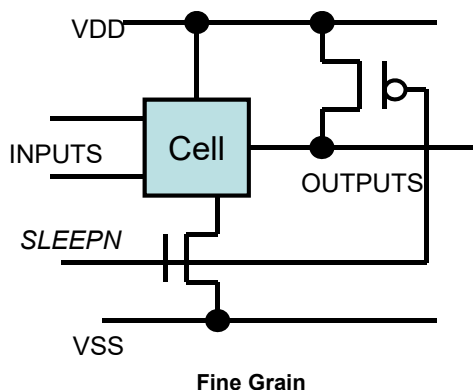
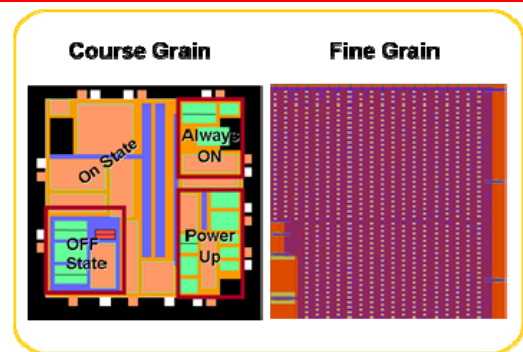
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A 2-stage pipelined 40-bit ALU (IBM)

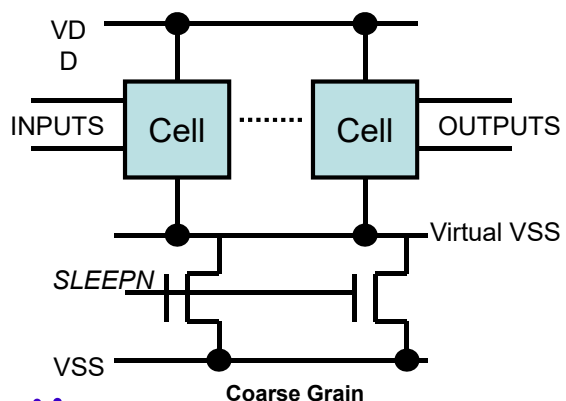
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Granularity of Power Switches

- **Fine Grain**
 - The switch is placed inside each cell
 - Better control, but larger area overhead
- **Coarse Grain**
 - Connected on the permanent power
 - Easier to implement, but have performance penalty during power-up



Fine Grain



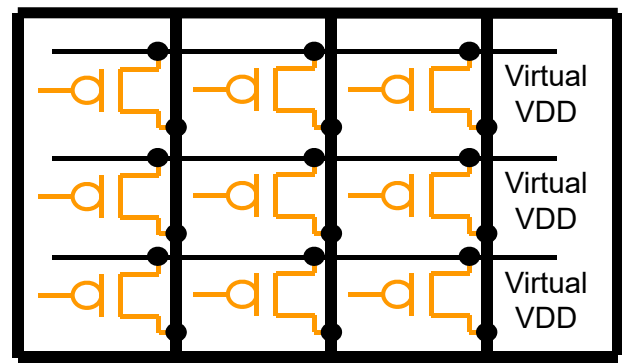
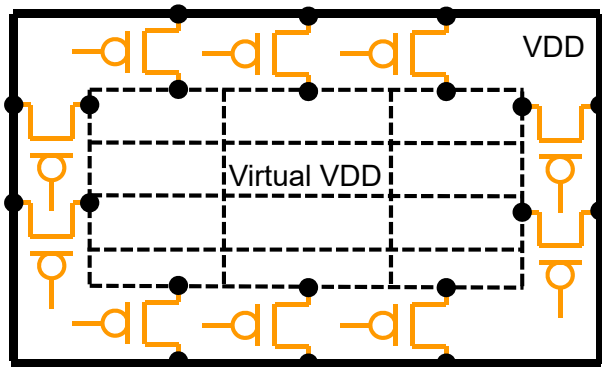
Coarse Grain

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Arrangement of Power Switches

- **Ring Style**
 - A ring of switches connects VDD to a switched or virtual VDD power mesh that covers the power gated block
 - Simpler power plan, but larger area overhead
- **Grid Style**
 - The sleep transistors are distributed throughout the power gated region.
 - Less area and performance overhead, but increase routing complexity

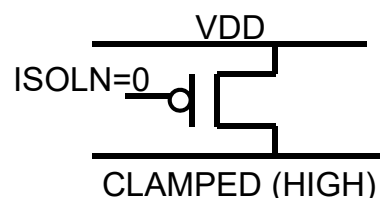
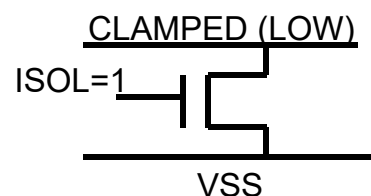
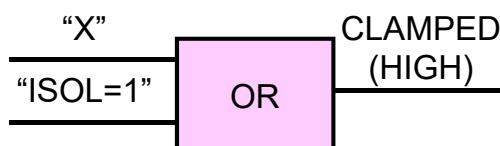
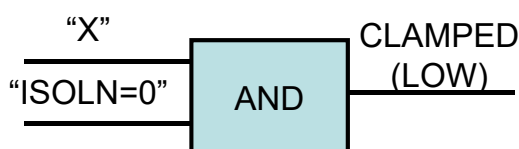


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Signal Isolation

- **Without power supply, the output signals will become floating**
 - Isolation cells are required to stop the propagation of those signals
- **For timing consideration, the isolation transistor can be used to clamp the output signal**



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State Retention and Restoration

- **Before shutting down the power supply, the register states must be kept for future restoration**
- **To resume the operation of the gated blocks**
 - The retention state must be restored when the block is powered up
- **State retention and restoration strategies**
 - A software approach that reads and writes registers
 - A scan-based approach that uses scan chains to store states off chip
 - A register-based approach that uses built-in retention registers

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Software Approach

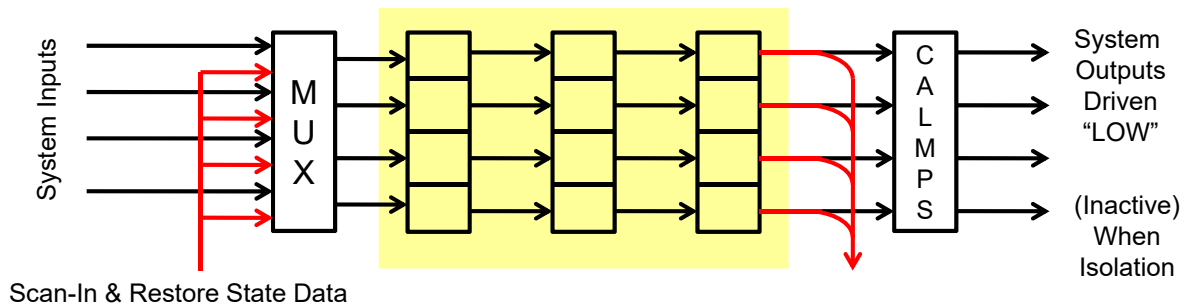
- **Software approach flow**
 - During the power shutdown sequence, a processor **reads the registers** of the power gated blocks
 - The states are stored in the **processor's memory**
 - During the power up sequence, the processor reads its memory and **write the states back** into the power gated blocks
- **Drawbacks**
 - The **bus traffic** slows the power down and up sequence
 - **Bus conflicts** can make the store/restore times no-deterministic
 - Software must be written and **integrated** into the system's software for handling power down and up

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Scan-Based Approach

- Reusing scan chains for manufacturing test to perform state retention has no area overhead
- Scan-based approach flow
 - During power down, the registers are shifted out as in scan testing mode and stored into the memory
 - During power up, the memory states are shifted in by scan chains
- Shifting the register states out and back is extra energy cost

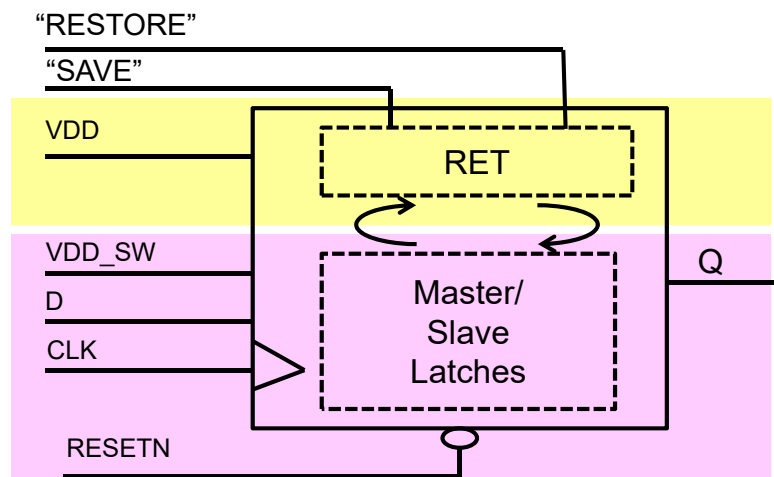


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Register-Based Approach

- Build in a “shadow” register to preserve the register states during power down and restore it at power up
 - The shadow register is always powered on for state retention
- Easier for implementation, but have larger area overhead



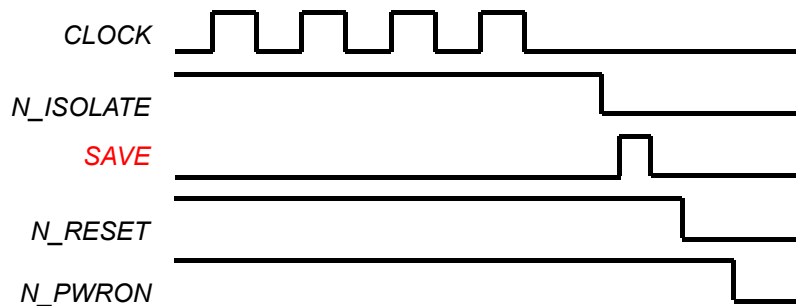
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Power Control Sequence (1/2)

- **To shut down power**

- Flush through any bus or external operations in progress
- Stop the clocks in the appropriate phase to minimize leakage into the power-gated region
- Assert the isolation control signal to park all outputs in a safe conditions
- Assert the state retention save condition
- Assert reset to the block, so that it powers up in the reset condition
- Assert the power gating control signal to power down the block



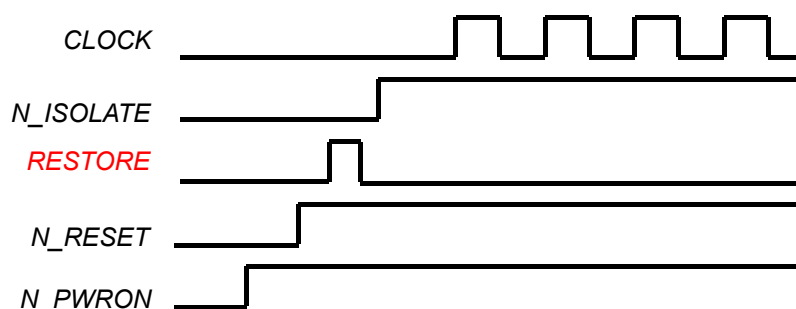
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Power Control Sequence (2/2)

- **To restore power**

- De-assert the power gating control signal to restore power back
- De-assert reset to ensure clean initialization following the gated power-up
- Assert the state retention restore condition
- De-assert the isolation control signal to restore all outputs
- Restart the clocks

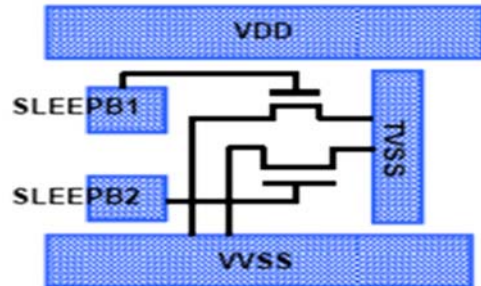


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Power-On Rush Current

- **There is a large current rush in sleep-to-active transition which can cause EM and IR-drop issues**
 - Also called “in-rush current”
- **Using parallel (mother-daughter) sleep transistors can reduce rush current**
 - Optimizing the ratio of the daughter and mother transistor widths
 - Scheduling the turn-on times of the two switches so as to minimize the wakeup delay
- **Power-up scheduling is another useful technique**
 - Scheduling the turn-on times of different blocks to avoid current rush and reduce the peak current



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Summary of Power Gating Approach

- **Power gating design can reduce the leakage power when the block is powered off**
 - Using High-VT transistors to limit the leakage current
- **Power gating design is composed of**
 - Power switch fabric
 - Isolation and retention cell
 - Power controller
- **Performance degradation should be prevented**
 - Performance becomes worse because IR-drop effects on normal operation mode
 - In-rush current during power-up can cause extra supply noise issues

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Conclusion

- **Low-power design is a major trend on today's applications**
 - Portable devices, medical devices, bio-electronics, ...
 - Low-power techniques at higher design levels can reduce more power
- **Low-power techniques mentioned in this slide**
 - Reduce supply voltage ($V_{dd}\downarrow$)
 - Multiple power domains
 - Reduce signal transitions ($f\downarrow$)
 - Dynamic voltage and frequency scaling (DVFS)
 - Clock gating
 - Use high-Vt cells for lower leakage power ($leakage\downarrow$)
 - Dual threshold voltages, Mixed-Vt gates
 - Shut down power supply when not used ($V_{dd}\downarrow$, $leakage\downarrow$)
 - Power gating (MTCMOS)
- **Power management is important to control those mechanisms**

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Reference

- [1] Anand Raghunathan, Niraj K. Jha, Sujit Dey, "High-level power analysis and optimization" Boston : Kluwer Academic, c1998.
- [2] Michael Keating, David Flynn, Rob Aitken, Alan Gibbons, Kaijian Shi, "Low Power Methodology Manual: For System-on-Chip Design" Berlin, Germany : Springer-Verlag, 2007.
- [3] Pokhrel, K., "Physical and Silicon Measures of Low Power Clock Gating Success: An Apple to Apple Case Study", SNUG, 2007.
- [4] Frank Sill, Claas Cornelius, Stephan Kubisch, Dirk Timmermann, "Mixed Gates: Leakage Reduction techniques applied to Switches for Networks-on-Chip", ReCoSoC, 2006.
- [5] Karen Yorav, "The challenges of low power design", Tutorial , Haifa Verification Conference 2008.

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